



# 4-String, Max 400mA/String, 80V Return, Step-Up WLED Controller

#### DESCRIPTION

The MP3398H is a step-up controller with four LED current channels, designed to drive WLED arrays for large LCD panel backlighting applications. The MP3398H can expand the number of LED channels with two or more ICs in parallel sharing a single power source.

The MP3398H employs peak current control mode with a fixed switching frequency ( $f_{SW}$ ) that is configurable via an external setting resistor. The MP3398H drives an external MOSFET to boost the output voltage ( $V_{OUT}$ ) from a 4.5V to 33V input voltage ( $V_{IN}$ ) supply. The device also regulates the current in each LED string to the value set by an external current-setting resistor.

The MP3398H applies four internal current sources for current balancing. It achieves 1.5% current matching regulation accuracy between the strings. The low regulation voltage on the LED current sources reduces power loss.

The MP3398H supports direct pulse-width modulation (PWM) dimming mode with a PWM input and analog dimming mode with a PWM input or DC input. Full protection features include over-current protection (OCP), over-temperature protection (OTP), under-voltage protection (UVP), over-voltage protection (OVP), LED short and open protection, and inductor and diode short protection.

The MP3398H is available in an SOIC-16 package.

#### **FEATURES**

- 4-String, Max 400mA/String WLED Driver
- 4.5V to 33V Input Voltage (V<sub>IN</sub>) Range
- 80V Absolute Maximum Rating for Each String
- 1.5% Current Matching Accuracy between Each String
- Direct Pulse-Width Modulation (PWM)
   Dimming Mode
- Analog Dimming Mode via PWM Input or DC Input
- Cascading Capability with a Single Power Source
- LED Open and Short Protection
- Configurable, Recoverable Over-Voltage Protection (OVP)
- 540mV Cycle-by-Cycle Current Limit
- Hiccup Over-Temperature Protection (OTP)
- Short Inductor and Diode Protection
- Available in an SOIC-16 Package

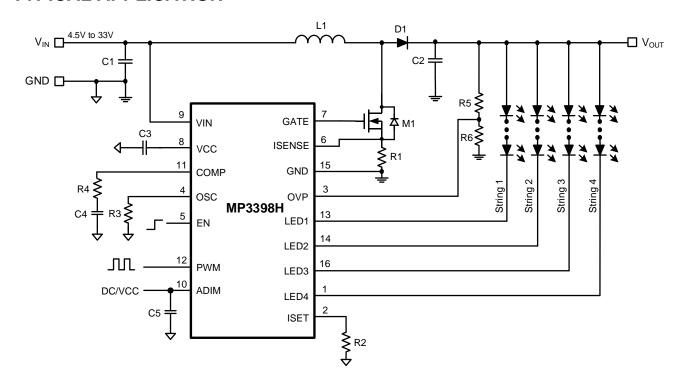
#### **APPLICATIONS**

- Desktop LCD Flat-Panel Displays
- All-in-One PCs
- 2D and 3D LCD TVs

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## **TYPICAL APPLICATION**





## **ORDERING INFORMATION**

Part Number*	Package	Top Marking	MSL Rating
MP3398HGS	SOIC-16	See Below	2

<sup>\*</sup> For Tape & Reel, add suffix -Z (e.g. MP3398HGS-Z).

TOP MARKING

MPSYYWW

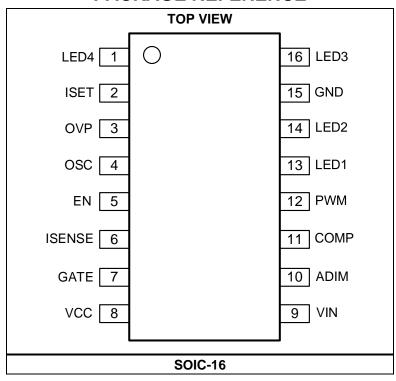
MP3398H

LLLLLLLL

MPS: MPS prefix YY: Year code WW: Week code

MP3398H: Part number LLLLLLLL: Lot number

#### **PACKAGE REFERENCE**





## **PIN FUNCTIONS**

D: #	Nama	Description
Pin #	Name	Description
1	LED4	<b>LED string 4 current input.</b> The LED4 pin is the open-drain output of an internal dimming control switch. Connect LED4 to the LED string 4 cathode.
2	ISET	<b>LED current (ILED) setting.</b> Connect a current-setting resistor from the ISET pin to ground to configure the current for each LED string.
3	OVP	Output over-voltage protection (OVP). Connect a resistor divider from the output to the OVP pin to configure the OVP threshold.
4	OSC	<b>Switching frequency (fsw) setting.</b> Connect a resistor (Rosc) between the OSC pin and GND to set the step-up converter's fsw. The clock frequency is proportional to the current sourced from OSC.
5	EN	<b>Enable control input.</b> Pull EN above 1.5V to turn on the part; pull EN below 0.6V to turn off the part. Do not float the EN pin.
6	ISENSE	<b>Current-sense input.</b> During normal operation, the ISENSE pin senses the voltage across the external inductor current-sense resistor (R <sub>SENSE</sub> ) for peak current control mode. ISENSE also limits the inductor current (I <sub>L</sub> ) during every switching cycle. If the MP3398H is used for cascading applications, connect the slave IC's ISENSE pin to GND. Do not float ISENSE.
7	GATE	<b>Power MOSFET driver output for the step-up converter.</b> The GATE pin drives the external N-channel power MOSFET.
8	VCC	<b>Internal 5.9V linear regulator output.</b> The VCC pin provides the power supply for the external MOSFET gate driver and the internal control circuitry. Bypass VCC to GND using a ceramic capacitor.
9	VIN	Supply input. The VIN pin must be bypassed locally.
10	ADIM	Input signal for analog brightness control. For analog dimming with a pulse-width modulation (PWM) input, connect a capacitor between the ADIM pin and GND, then apply a PWM signal to the PWM pin. The $I_{\text{LED}}$ amplitude is determined by the duty cycle of the PWM signal applied to PWM. An internal $100\text{k}\Omega$ resistor combined with an external capacitor form the filter that is used to obtain the $I_{\text{LED}}$ reference. A frequency exceeding $20\text{kHz}$ is recommended to achieve improved PWM signal filtering performance. For analog dimming with a DC input, pull PWM high to VCC or pull PWM down to GND, then apply a $0\text{V}$ to $1.5\text{V}$ DC voltage on ADIM to adjust the $I_{\text{LED}}$ amplitude from $0\%$ to $100\%$ .
11	COMP	<b>Step-up converter compensation.</b> The COMP pin compensates for the regulation control loop. Connect a ceramic capacitor or a resistor combined with a capacitor from COMP to GND.
12	PWM	Input signal for PWM brightness control. For direct PWM dimming, pull ADIM high to VCC, then apply a PWM signal to PWM. ILED is chopped and the average ILED is equal to ISET x DDIM, where ISET is the ILED amplitude set by a resistor between ISET and GND, and DDIM is the PWM dimming signal duty cycle. For analog dimming with a PWM input, apply a PWM signal exceeding 20kHz on PWM. Ensure that the high-level voltage exceeds 1.5V, and the low-level voltage is below 0.4V. If PWM is floating, weakly pull PWM to GND internally.
13	LED1	<b>LED string 1 current input.</b> The LED1 pin is the open-drain output of an internal dimming control switch. Connect LED1 to the LED string 1 cathode.
14	LED2	<b>LED string 2 current input.</b> The LED2 pin is the open-drain output of an internal dimming control switch. Connect LED2 to the LED string 2 cathode.
15	GND	Ground.
16	LED3	<b>LED string 3 current input.</b> The LED3 pin is the open-drain output of an internal dimming control switch. Connect LED3 to the LED string 3 cathode.

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## **ABSOLUTE MAXIMUM RATINGS (1)** V<sub>IN</sub> .....-0.3V to +40V $V_{LED1}$ to $V_{LED4}$ .....-0.3V to +80V All other pins .....-0.3V to +6.5V Continuous power dissipation (T<sub>A</sub> = 25°C) (2) SOIC-16......1.56W Junction temperature ......150°C Lead temperature ......260°C

## Recommended Operating Conditions (3)

Storage temperature ..... -60°C to +150°C

Supply voltage (V <sub>IN</sub> )	4.5V to 33V
Max LED current (I <sub>LED_MAX</sub> )	400mA
Operating junction temp	40°C to +125°C

Thermal Resistance (4)	$oldsymbol{ heta}_{JA}$	$\boldsymbol{\theta}$ JC	
SOIC-16	80	35	°C/W

#### Notes:

- 1) Exceeding these ratings may damage the device.
- The maximum allowable power dissipation is a function of the maximum junction temperature, T<sub>J</sub> (MAX), the junction-toambient thermal resistance,  $\theta_{\text{JA}}$ , and the ambient temperature, TA. The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $P_D$  (MAX) = (T\_J (MAX) - T\_A) /  $\theta_{JA}.$  Exceeding the maximum allowable power dissipation can produce an excessive die temperature, which may cause the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- The device is not guaranteed to function outside of its operating conditions.
- Measured on JESD51-7, a 4-layer PCB.



## **ELECTRICAL CHARACTERISTICS**

 $V_{IN}$  = 12V,  $V_{EN}$  = 5V,  $T_A$  = 25°C, unless otherwise noted.

Parameters	Symbol	Condition	Min	Тур	Max	Unit
General						
Operating input voltage	V <sub>IN</sub>		4.5		33	V
Quiescent supply current	Ιq	V <sub>IN</sub> = 12V, no switching		3.85	4.5	mA
Shutdown supply current	I <sub>ST</sub>	$V_{EN} = 0V$ , $V_{IN} = 12V$			1	μΑ
Low-dropout (LDO) output voltage	Vcc	7V < V <sub>IN</sub> < 28V, 0 < I <sub>VCC</sub> < 10mA	5.5	5.9	6.3	V
V <sub>CC</sub> under-voltage lockout (UVLO) threshold	Vcc_uvlo	Rising edge	3.7	4	4.3	V
Vcc UVLO hysteresis				350		mV
EN high voltage	V <sub>EN_HIGH</sub>	V <sub>EN</sub> rising	1.5			V
EN low voltage	V <sub>EN_LOW</sub>	V <sub>EN</sub> falling			0.6	V
Step-Up Converter		- Liv .eg	_			<u> </u>
Gate driver source						
impedance		$V_{CC} = 5.9V, V_{GATE} = 5.9V$		4		Ω
Gate driver sink impedance		Vcc = 5.9V, Igate = 10mA		2.5		Ω
Switching frequency	fsw	$Rosc = 100k\Omega$	400	500	600	kHz
Maximum duty cycle	D <sub>MAX</sub>	$Rosc = 100k\Omega$	90			%
Cycle-by-cycle ISENSE current limit			480	540	600	mV
Latch-off current limit			720	800	880	mV
COMP source current limit	Icomp_soli	1V < COMP < 2.9V	120	30	000	μA
COMP sink current limit	ICOMP_SILI	1V < COMP < 2.9V		18		μA
COMP transconductance	GCOMP_SILI	$\Delta I_{COMP} = \pm 10 \mu A$		120		μΑ/V
Current Dimming	OCOMP	ΔICOMP = ±10μA	1	120		μ μ ν
PWM input low threshold	V <sub>PWM_LO</sub>	V <sub>PWM</sub> falling			0.4	V
PWM input high threshold	V <sub>PWM_HI</sub>	V <sub>PWM</sub> rising	1.5		0.4	V
ADIM input DC range	V PWW_HI V <sub>ADIM</sub>	VPWM HSHIG	0		1.5	V
Internal resister on ADIM	R <sub>ADIM</sub>		70	100	130	kΩ
Current Regulation	IXADIM		10	100	130	KZZ
ISET voltage	V <sub>ISET</sub>		1.46	1.5	1.54	V
LEDx average current	I <sub>LEDx</sub>	$R_{ISET} = 12k\Omega$	97	100	103	mA
Current matching (5)	ILEDX	I <sub>LED</sub> = 100mA	37	1	1.5	%
		I <sub>LED</sub> = 100mA		360	1.0	mV
LEDx regulation voltage		I <sub>LED</sub> = 60mA		285		mV
Protection	l	TEED COMMIT	1		<u>I</u>	1
Over-voltage protection	.,		1.5	_	0.1	
(OVP) threshold	Vovp		1.9	2	2.1	V
OVP UVLO threshold	Vovp_uvlo	Step-up converter fails		55		mV
LEDx UVLO threshold	V <sub>LEDx_UVLO</sub>			200		mV
LEDx over-voltage (OV)	_		7		_	
threshold	$V_{LEDx\_OV}$		7	8	9	V
Thermal protection threshold	T <sub>ST</sub>			150		°C
Thermal protection				25		°C
hysteresis				20		

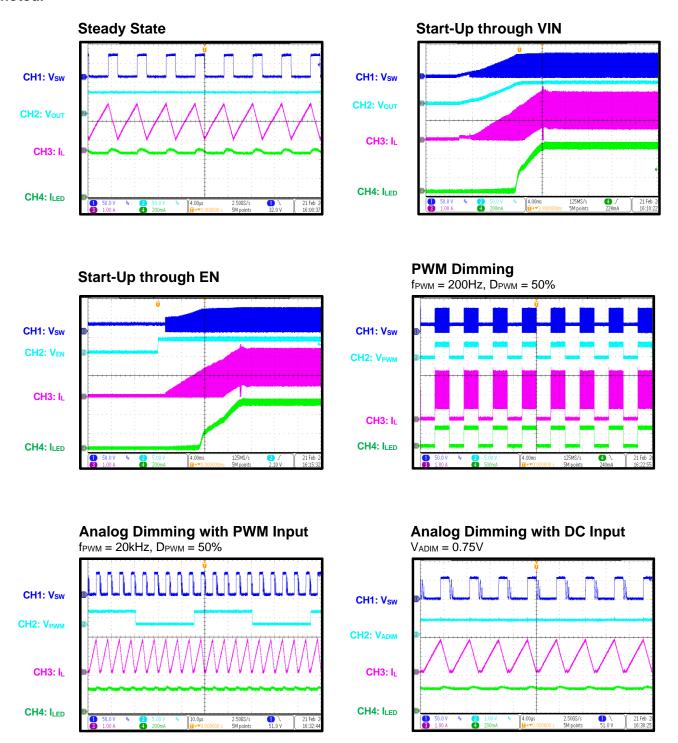
#### Note:

<sup>5)</sup> Matching is defined as the difference between the maximum to minimum current divided by twice the average current.



#### TYPICAL PERFORMANCE CHARACTERISTICS

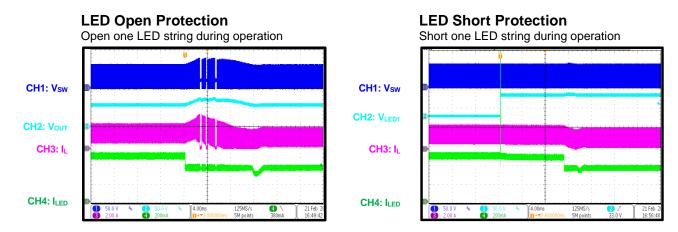
 $V_{\text{IN}}$  = 19V,  $V_{\text{EN}}$  = 3.3V, 120mA/string, 4 strings, 20 LEDs in series,  $T_{\text{A}}$  = 25°C, unless otherwise noted.

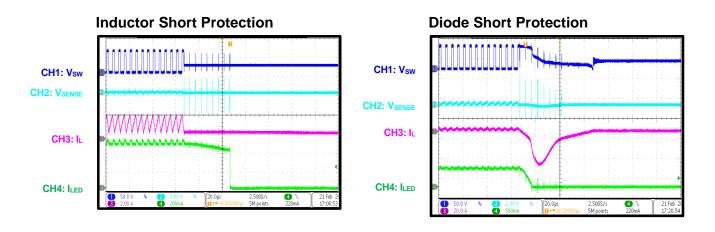


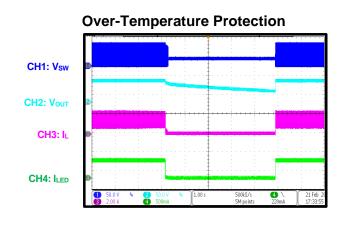


## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 $V_{\text{IN}}$  = 19V,  $V_{\text{EN}}$  = 3.3V, 120mA/string, 4 strings, 20 LEDs in series,  $T_{\text{A}}$  = 25°C, unless otherwise noted.









## **FUNCTIONAL BLOCK DIAGRAM**

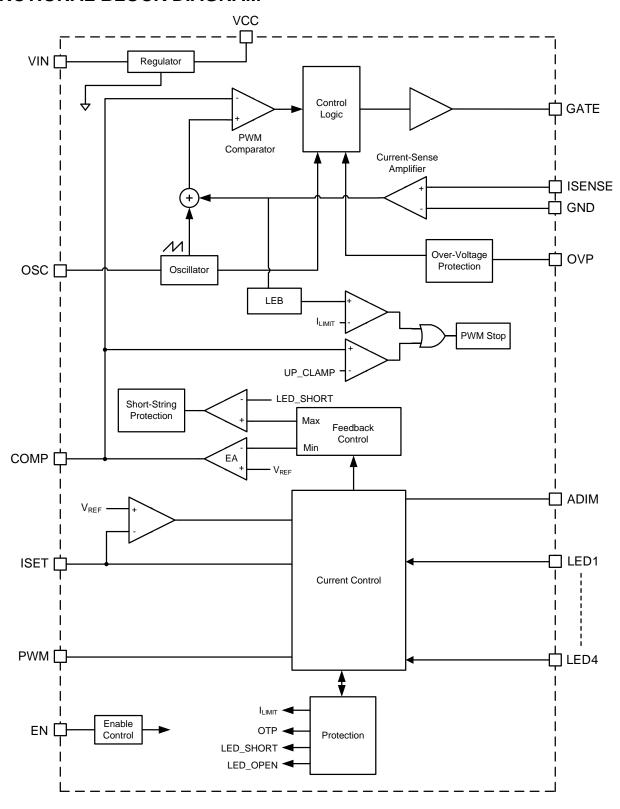


Figure 1: Functional Block Diagram



#### **OPERATION**

The MP3398H is a configurable, constant-frequency, peak current control mode, step-up converter with 4-channel regulated current sources to drive an array of up to four white LED strings.

#### Internal 5.9V Regulator

The MP3398H includes an internal linear regulator (VCC). When the input voltage ( $V_{IN}$ ) exceeds 6.5V, VCC outputs a 5.9V power supply to the external MOSFET gate driver and the internal control circuitry. The VCC voltage ( $V_{CC}$ ) drops to 0V when the chip shuts down. The MP3398H features under-voltage lockout (UVLO). The chip is disabled until  $V_{CC}$  exceeds the UVLO threshold. The UVLO hysteresis is approximately 350mV.

#### **System Start-Up**

When enabled, the MP3398H first checks the topology connection by monitoring the overvoltage protection (OVP) pin. This determines whether a Schottky diode is connected or the boost output is shorted to GND. An OVP voltage exceeding 55mV allows the chip to switch normally. Otherwise, switching is disabled. The MP3398H checks additional safety limits after passing the OVP test, including UVLO, over-temperature protection (OTP), and over-current protection (OCP). If all protection tests pass, then the chip begins boosting the step-up converter with an internal soft start (SS).

To prevent a large inrush current, it is recommended to apply the enable signal after establishing  $V_{\text{IN}}$  and the pulse-width modulation (PWM) dimming signal during the start-up sequence.

#### **Step-Up Converter**

At the beginning of each switching cycle, the internal clock turns on the external MOSFET. During normal operation, the minimum turn-on time for the external MOSFET is about 150ns. Add a stabilizing ramp to the current-sense amplifier's output to prevent subharmonic oscillations when the duty cycle exceeds 50%. Then the summed output of the stabilizing ramp and current-sense amplifier is fed into the PWM comparator. When the summed voltage

reaches the error amplifier (EA)'s output voltage (V<sub>COMP</sub>), the external MOSFET turns off.

 $V_{\text{COMP}}$  is an amplified signal of the difference between the reference voltage ( $V_{\text{REF}}$ ) and the feedback voltage ( $V_{\text{FB}}$ ). The converter automatically chooses the lowest active LEDx pin voltage ( $V_{\text{LEDx}}$ ) to provide a sufficient bus voltage to power all the LED arrays.

If  $V_{FB}$  drops below  $V_{REF}$ , then  $V_{COMP}$  increases. This results in more current flowing through the MOSFET, increasing the power delivered to the output and forming a closed loop that regulates the output voltage ( $V_{OUT}$ ).

Under light-load operation, especially if  $V_{\text{OUT}} \approx V_{\text{IN}}$ , the converter runs in pulse-skip mode. In this mode, the MOSFET turns on for a minimum on time and then the converter discharges the power to the output for the remaining period. The external MOSFET remains off until  $V_{\text{OUT}}$  must be boosted again.

#### **Dimming Control**

The MP3398H provides three flexible dimming methods: direct PWM dimming, analog dimming with a PWM input, and analog dimming with a DC input.

For direct PWM dimming, pull the ADIM pin high to VCC, then apply a PWM signal to the PWM pin. The LED current ( $I_{LED}$ ) is chopped by the PWM signal, and the average  $I_{LED}$  is equal to  $I_{SET}$  x  $D_{DIM}$ , where  $D_{DIM}$  is the PWM dimming signal duty cycle, and  $I_{SET}$  is the  $I_{LED}$  amplitude set by a resistor between ISET and GND.

For analog dimming with a PWM input, connect a capacitor between ADIM and GND, then apply a PWM signal to PWM. An internal  $100k\Omega$  resistor combined with an external capacitor form the filter that is used to obtain the  $I_{LED}$  amplitude reference. The  $I_{LED}$  amplitude is equal to  $I_{SET}$  x  $D_{DIM}$ , where  $D_{DIM}$  is the PWM dimming signal duty cycle, and  $I_{SET}$  is the  $I_{LED}$  amplitude set by a resistor between ISET and GND. A minimum 20kHz PWM signal is recommended to improve filtering.

For analog dimming with a DC input, pull PWM high to VCC or pull PWM down to GND,



then apply a 0V to 1.5V DC voltage on ADIM to adjust the  $I_{\text{LED}}$  amplitude from 0% to 100%.

## Operating Switching Frequency (fsw)

The MP3398H's switching frequency ( $f_{SW}$ ) is set via an external resistor ( $R_{OSC}$ ) on OSC, which optimizes the size of the external components and system efficiency.

#### **Open-String Protection**

Open-string protection is achieved by detecting the OVP pin voltage and  $V_{LEDx}$  (where "LEDx" can be LED1, LED2, LED3, or LED4). If one or more strings are open, then the respective LEDx pins are pulled to ground, and the IC continues charging  $V_{OUT}$  until it reaches the OVP threshold. If the OVP threshold is triggered, then the chip stops switching and marks off the strings for which  $V_{LEDx}$  is below 200mV. Once marked, the remaining LED strings force  $V_{OUT}$  back to normal regulation. The string with the largest voltage drop determines the output regulation value.

The MP3398H always attempts to light at least one string. If all strings are open, the MP3398H shuts down the step-up converter. The strings remain in this marked state until the chip resets.

#### **Short-String Protection**

The MP3398H monitors  $V_{LEDx}$  to determine whether a short-string fault has occurred. If one or more strings are shorted, then the respective LEDx pins tolerate high-voltage stress. If  $V_{LEDx}$  exceeds the protection threshold, then short-string fault protection is triggered. When a short-string fault remains for 10ms, the fault

string is marked off and disabled. Once a string is marked off, it disconnects from the  $V_{\text{OUT}}$  loop until  $V_{\text{IN}}$  or EN restarts.

To prevent mistriggering an LED short protection when the LED string is open, the LED short protection function is disabled when all the used LED channels' V<sub>LEDx</sub> exceeds 2.1V.

#### Cycle-by-Cycle Current Limit

To prevent the external components from exceeding their respective current stress ratings, the IC employs cycle-by-cycle current-limit protection. If the current exceeds the current limit threshold, the IC stops switching until the next clock cycle.

#### **Short Inductor and Diode Protection**

When the external inductor or diode is shorted, the IC provides protection by detecting the current flowing through the power MOSFET. Once the current-sense voltage across the current-sense resistor (R<sub>SENSE</sub>, connected between ISENSE and GND) reaches the current protection threshold and lasts for eight switching cycles, the IC stops switching and latches off.

#### Thermal Shutdown

The MP3398H monitors the silicon die temperature to prevent the IC from operating at exceedingly high temperatures. If the die temperature exceeds the upper threshold ( $T_{\rm ST}$ ), the IC shuts down. Once the die temperature drops below the lower threshold, the IC starts up again and resumes normal operation. The typical hysteresis value is about 25°C.



#### APPLICATION INFORMATION

## **Selecting the Switching Frequency**

The step-up converter's  $f_{SW}$  is recommended to be between 100kHz and 900kHz for most applications.  $R_{OSC}$  sets the internal  $f_{SW}$  for the step-up converter, which can be calculated with Equation (1):

$$f_{SW}(kHz) = \frac{50000}{R_{OSC}(k\Omega)}$$
 (1)

For example, if  $R_{OSC}$  is set to  $100k\Omega$ , then  $f_{SW}$  is set to 500kHz.

#### **Setting the LED Current**

The current in each LED string is set via the current-setting resistor on ISET (R<sub>ISET</sub>). I<sub>LED</sub> can be calculated with Equation (2):

$$I_{LED}(mA) = \frac{1200}{R_{ISET}(k\Omega)}$$
 (2)

If  $R_{\text{ISET}}$  is set to 12k $\Omega$ , then  $I_{\text{LED}}$  is set to 100mA. Do not leave ISET open.

#### Selecting the Input Capacitor

The input capacitor ( $C_{IN}$ ) reduces the surge current drawn from the input supply as well as the switching noise from the device. The  $C_{IN}$  impedance at  $f_{SW}$  should be below the input source impedance to prevent high-frequency switching current from passing through to the input. Ceramic capacitors with X5R or X7R dielectrics are recommended for their low-ESR and small temperature coefficients. For most applications, it is recommended to use a  $4.7\mu F$  ceramic capacitor in parallel with a  $220\mu F$  electrolytic capacitor.

## Selecting the Inductor and Current-Sense Resistor

A larger-value inductor results in reduced ripple current and peak inductor current (I<sub>L\_PEAK</sub>), which reduces stress on the N-channel MOSFET. However, it also has a larger physical size, higher series resistance, and lower saturation current. Choose an inductor that does not saturate under the worst-case load conditions. Select the minimum inductance to ensure that the boost converter works in continuous conduction mode (CCM) with high efficiency and good EMI performance.

The required inductance (L) can be calculated with Equation (3):

$$L \ge \frac{\eta \times V_{OUT} \times D \times (1-D)^2}{2 \times f_{SW} \times I_{OAD}}$$
 (3)

Where  $I_{LOAD}$  is the LED load current,  $\eta$  is the efficiency, and D is the switching duty cycle.

D can be calculated with Equation (4):

$$D = 1 - \frac{V_{IN}}{V_{OUT}} \tag{4}$$

The switching current is used for peak current control mode. To avoid reaching the current limit, the voltage across the current-sense resistor ( $R_{\text{SENSE}}$ ) must be below 80% of the current limit voltage ( $V_{\text{SENSE}}$ ) in the worst-case scenario.  $R_{\text{SENSE}}$  can be calculated with Equation (5):

$$R_{SENSE} = \frac{0.8 \times V_{SENSE}}{I_{L PEAK}}$$
 (5)

I<sub>L PEAK</sub> can be calculated using Equation (6):

$$I_{\text{L\_PEAK}} = \frac{V_{\text{OUT}} \times I_{\text{LOAD}}}{\eta \times V_{\text{IN}}} + \frac{V_{\text{IN}} \times (V_{\text{OUT}} - V_{\text{IN}})}{2 \times L \times f_{\text{SW}} \times V_{\text{OUT}}}$$
 (6)

#### **Selecting the Power MOSFET**

The MP3398H can drive a wide variety of N-channel MOSFETS. The critical MOSFET selection parameters include maximum drain-to-source voltage ( $V_{DS\_MAX}$ ), maximum current ( $I_{D\_MAX}$ ), on resistance ( $R_{DS(ON)}$ ), gate-source charge ( $Q_{GS}$ ) and gate-drain charge ( $Q_{GD}$ ), and total gate charge ( $Q_{G}$ ).

Ideally, the off-state voltage across the MOSFET is equal to  $V_{\text{OUT}}$ . Consider the voltage spike when the MOSFET turns off, where  $V_{\text{DS\_MAX}}$  should be 1.5 times greater than  $V_{\text{OUT}}$ .

The maximum current through the power MOSFET occurs at the minimum  $V_{IN}$  ( $V_{IN\_MIN}$ ) and the maximum output power. The maximum RMS current through the MOSFET ( $I_{RMS\_MAX}$ ) can be calculated using Equation (7):

$$I_{\text{RMS\_MAX}} = I_{\text{IN\_MAX}} \times \sqrt{D_{\text{MAX}}}$$
 (7)

Where  $I_{\text{IN\_MAX}}$  is the maximum input current and  $D_{\text{MAX}}$  is the maximum switching duty cycle.



D<sub>MAX</sub> can be calculated with Equation (8):

$$D_{MAX} \approx \frac{V_{OUT} - V_{IN\_MIN}}{V_{OUT}}$$
 (8)

The MOSFET's current rating should be 1.5 times greater than  $I_{RMS\_MAX}$ .

The MOSFET's  $R_{DS(ON)}$  determines the conduction loss ( $P_{COND}$ ), which can be calculated with Equation (9):

$$P_{COND} = I_{RMS}^{2} \times R_{DS(ON)} \times k$$
 (9)

Where k is the MOSFET's temperature coefficient.

The switching loss is related to  $Q_{GD}$  and  $Q_{GS1}$ , which determine the commutation time.  $Q_{GS1}$  is the charge between the threshold voltage and the plateau voltage when a driver charges the gate, and can be read in the  $V_{GS}$  vs.  $Q_{G}$  chart in the MOSFET datasheet.  $Q_{GD}$  is the charge during the plateau voltage.

These two parameters are required to estimate the turn-on and turn-off losses (P<sub>SW</sub>), which can be calculated with Equation (10):

$$\begin{split} P_{SW} &= \frac{Q_{GS1} \times R_G}{V_{DR} - V_{TH}} \times V_{DS} \times I_{IN} \times f_{SW} + \\ &= \frac{Q_{GD} \times R_G}{V_{DR} - V_{PLT}} \times V_{DS} \times I_{IN} \times f_{SW} \end{split} \tag{10}$$

Where  $V_{TH}$  is the threshold voltage,  $V_{PLT}$  is the plateau voltage,  $V_{DS}$  is the drain-source voltage, and  $R_G$  is the gate resistance.

 $R_{G}$  is recommended to be between  $10\Omega$  and  $20\Omega.$ 

Note that calculating the switching loss is the most difficult part of loss estimation. Equation (10) provides a simplified equation. For more accurate estimates, the equation becomes much more complex.

 $Q_G$  is used to calculate the gate drive loss ( $P_{DR}$ ), which can be calculated with Equation (11):

$$P_{DR} = Q_{G} \times V_{DR} \times f_{SW}$$
 (11)

Where  $V_{DR}$  is the drive voltage.

#### Selecting the Output Capacitor

The output capacitor ( $C_{\text{OUT}}$ ) keeps the  $V_{\text{OUT}}$  ripple small and ensures feedback loop stability.  $C_{\text{OUT}}$  impedance must be low at  $f_{\text{SW}}$ . Ceramic capacitors with X7R dielectrics are recommended for their low ESR characteristics. For most applications, a 4.7 $\mu$ F ceramic capacitor in parallel with a 22 $\mu$ F to 47 $\mu$ F electrolytic capacitor is sufficient.

## Setting the Over-Voltage Protection (OVP) Threshold

Open-string protection is achieved through detecting the OVP pin voltage. In some cases, an LED string failure results in  $V_{FB}$  remaining at 0V. The MP3398H continues boosting  $V_{OUT}$  higher and higher. If  $V_{OUT}$  reaches the configured OVP threshold, then OVP is triggered.

To ensure that the chip functions properly, an appropriate  $V_{\text{OVP}}$  is required. The recommended OVP level is about 1.1 to 1.2 times greater than  $V_{\text{OUT}}$  for normal operation.  $V_{\text{OVP}}$  is set via a resistor divider from the output to the OVP pin, and can be calculated with Equation (12):

$$V_{OVP} = 2V \times \left(1 + \frac{R_{HIGH}}{R_{LOW}}\right) \tag{12}$$

#### **Expanding LED Channels**

The MP3398H can expand the number of LED channels by using two or three ICs in parallel. To connect two ICs for a total of eight LED strings, connect the master IC's VCC pins to the slave IC's VCC pins, which powers the slave IC internal logic circuitry. Connect the slave IC's COMP pins to the master IC's COMP pins to regulate the voltage of all eight LED strings. The slave IC's MOSFET driving signal is not used. The boost converter can only be driven by the master IC. Do not leave the slave IC's ISENSE pin floating; instead, connect it to ground. Apply the EN and DIM signals to both ICs.



#### **PCB Layout Guidelines**

Efficient PCB layout is critical to reduce EMI noise and achieve stable operation. For the best results, refer to Figure 2 and follow the guidelines below:

- A high-frequency pulse current flows through the loop between the external MOSFET, output diode, C<sub>OUT</sub>, and R<sub>SENSE</sub>. Keep this loop as small and short as possible.
- 2. Separate the power ground and signal ground to reduce noise affection.
- 3. Connect the power ground and signal ground together. All logic signals refer to the signal ground.
- 4. Place the ceramic capacitors for VIN and VCC as close to the IC as possible.

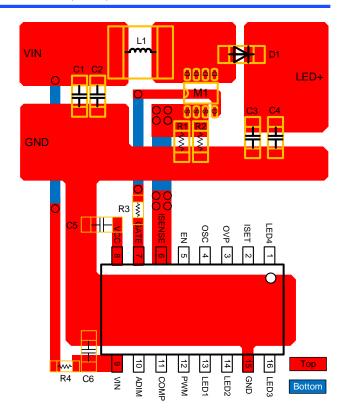


Figure 2: Recommended PCB Layout



## TYPICAL APPLICATION CIRCUIT

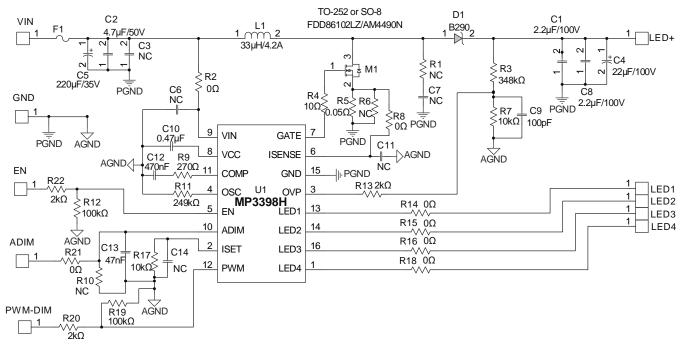


Figure 3: Typical Application Circuit (4-String, 20 LEDs in Series, 120mA/String)

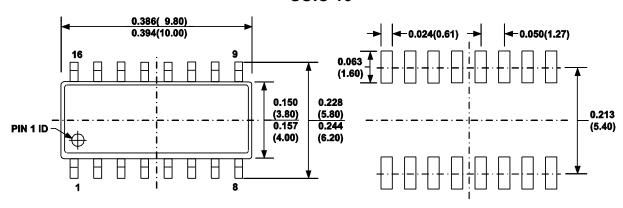
#### Note:

6) Some component values may need to be adjusted for different application conditions.



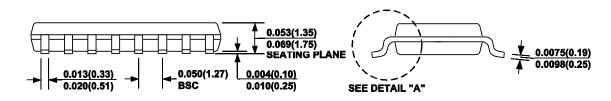
#### **PACKAGE INFORMATION**

#### SOIC-16



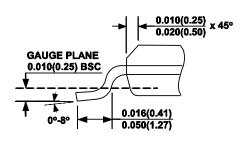
**TOP VIEW** 

**RECOMMENDED LAND PATTERN** 



**FRONT VIEW** 

**SIDE VIEW** 



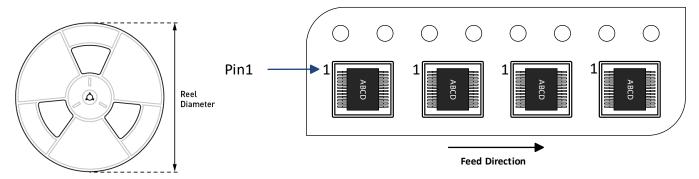
**DETAIL "A"** 

#### **NOTE:**

- 1) CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS IN MILLIMETERS.
- 2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
- 5) DRAWING CONFORMS TO JEDEC MS-012, VARIATION AC.
- 6) DRAWING IS NOT TO SCALE.



## **CARRIER INFORMATION**



Part Number	Package	Quantity/	Quantity/	Quantity/	Reel	Carrier	Carrier
	Description	Reel	Tube	Tray	Diameter	Tape Width	Tape Pitch
MP3398HGS-Z	SOIC-16	2500	50	N/A	13in	16mm	8mm



## **REVISION HISTORY**

Revision #	Revision Date	Description	Pages Updated
1.0	9/16/2022	Initial Release	-

**Notice:** The information in this document is subject to change without notice. Please contact MPS for current specifications. Users should warrant and guarantee that third-party Intellectual Property rights are not infringed upon when integrating MPS products into any application. MPS will not assume any legal responsibility for any said applications.

9/16/2022